

EL 465682468

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/388,826
Priority Filing Date September 1, 1999
Inventor Weimin Li et al.
Assignee Micron Technology, Inc.
Priority Group Art Unit 2812
Priority Examiner M. Whipple
Attorney's Docket No. MI22-1398
Title: Low k Interlevel Dielectric Layer Fabrication Methods

PRELIMINARY AMENDMENT

To: Assistant Commissioner for Patents
Washington, D.C. 20231

From: Mark S. Matkin (Tel. 509-624-4276; Fax 509-838-3424)
Wells, St. John, Roberts, Gregory & Matkin P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828

Sir:

Please enter the following amendments prior to examining the above-identified application. Applicant amends and remarks as follows: [unless otherwise indicated, deletions are bracketed, additions are underlined].

AMENDMENTSIn the Specification

At p. 2, line 15, replace "a exemplary" with --an exemplary--.

IA